

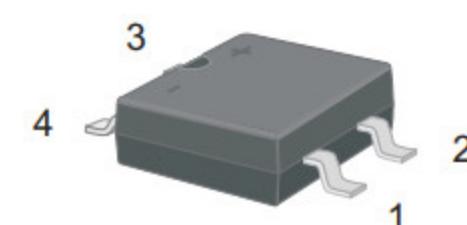
0.8A SURFACE MOUNT GLASS PASSIVATED BRIDGE RECTIFIER

FEATURES:

Glass Passivated Chip Junction
 Reverse Voltage - 100 to 1000 V
 Forward Current - 1.0 A
 High Surge Current Capability
 Designed for Surface Mount Application

PINNING

PIN	DESCRIPTION
1	Input Pin (~)
2	Input Pin (~)
3	Output Anode (+)
4	Output Cathode (-)



MBS Package

MECHANICAL DATA

- Case: MBS
- Terminals: Solderable per MIL-STD-750, Method 2026
- Approx. Weight: 100mg /0.0035oz

Maximum Ratings and Electrical characteristics

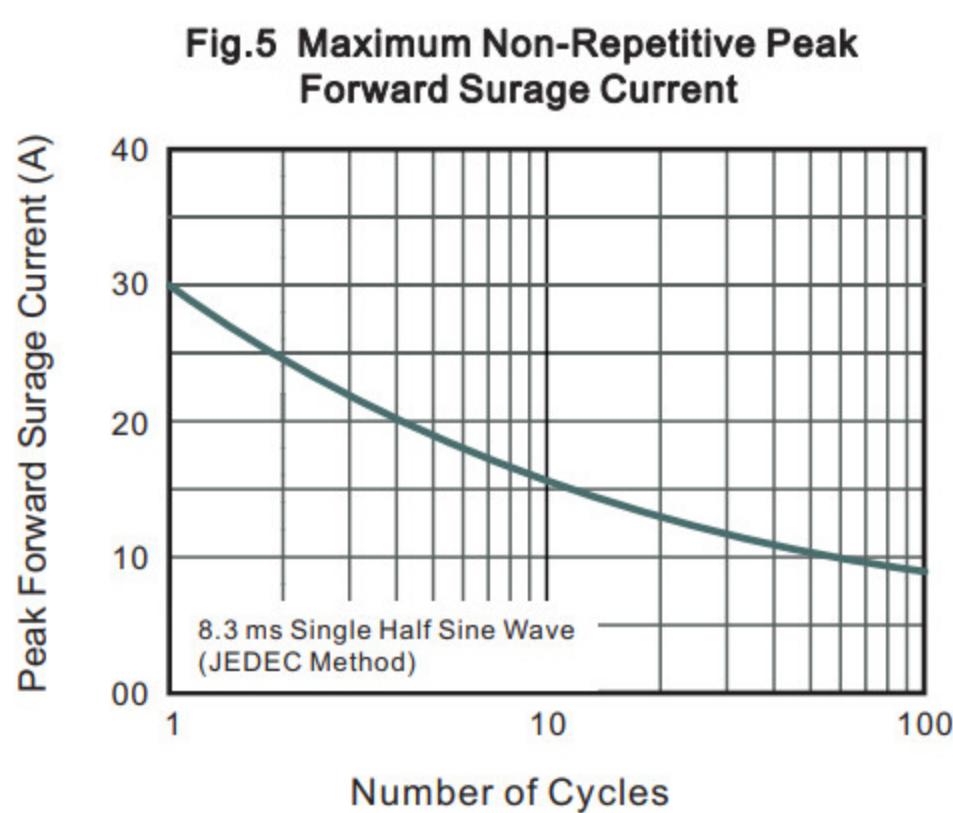
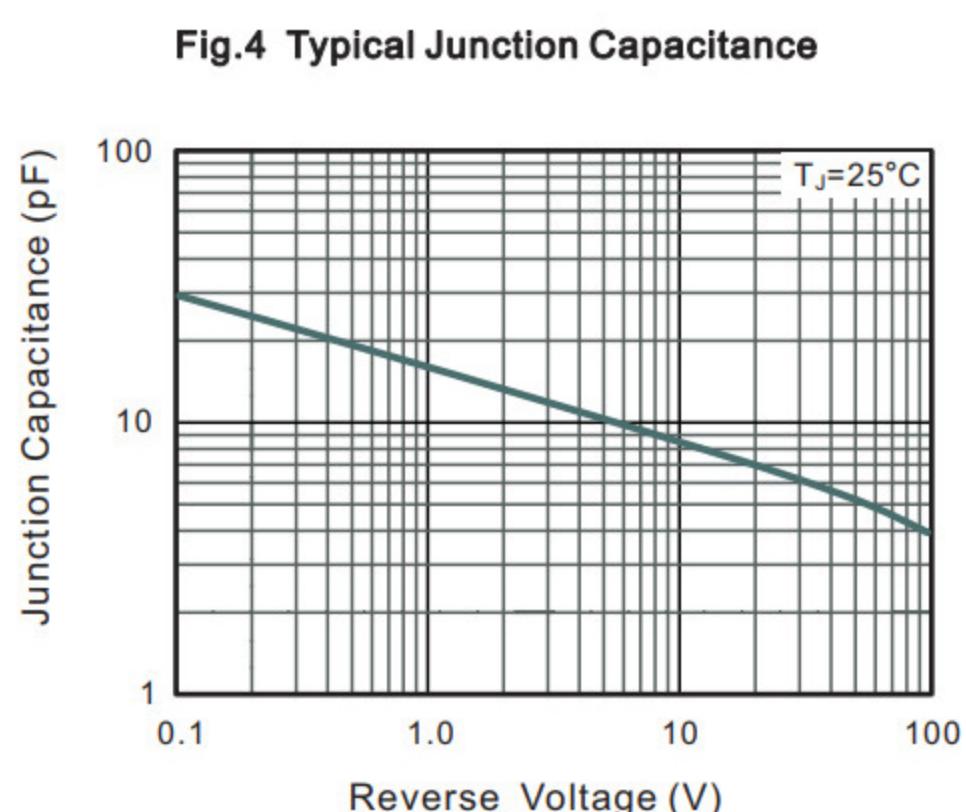
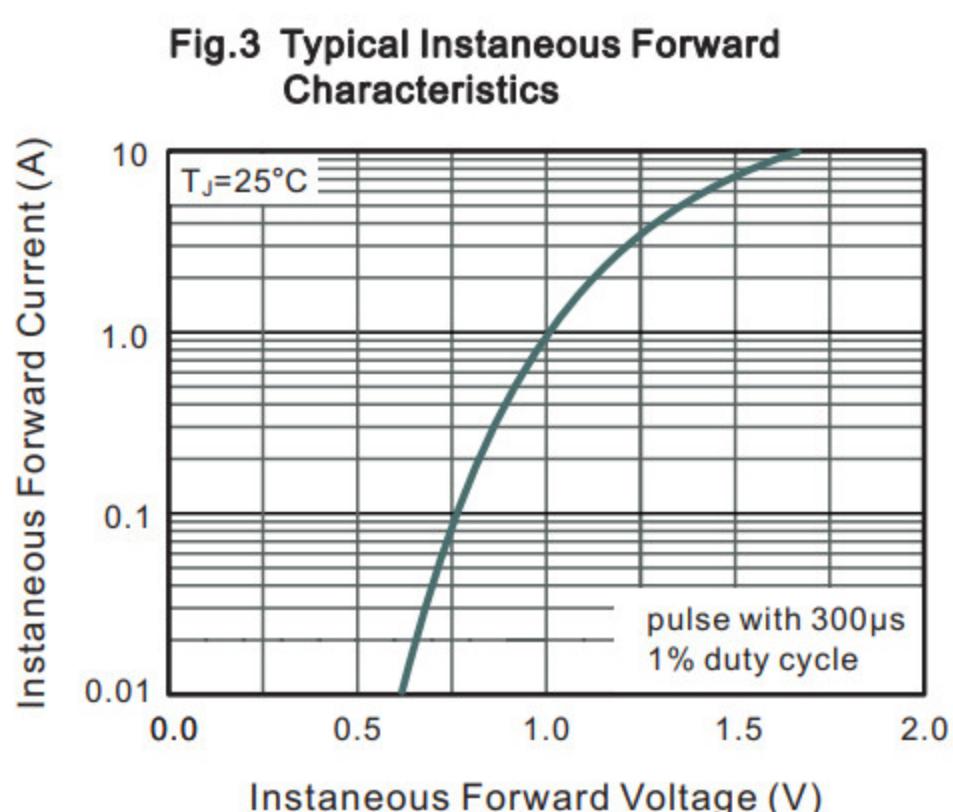
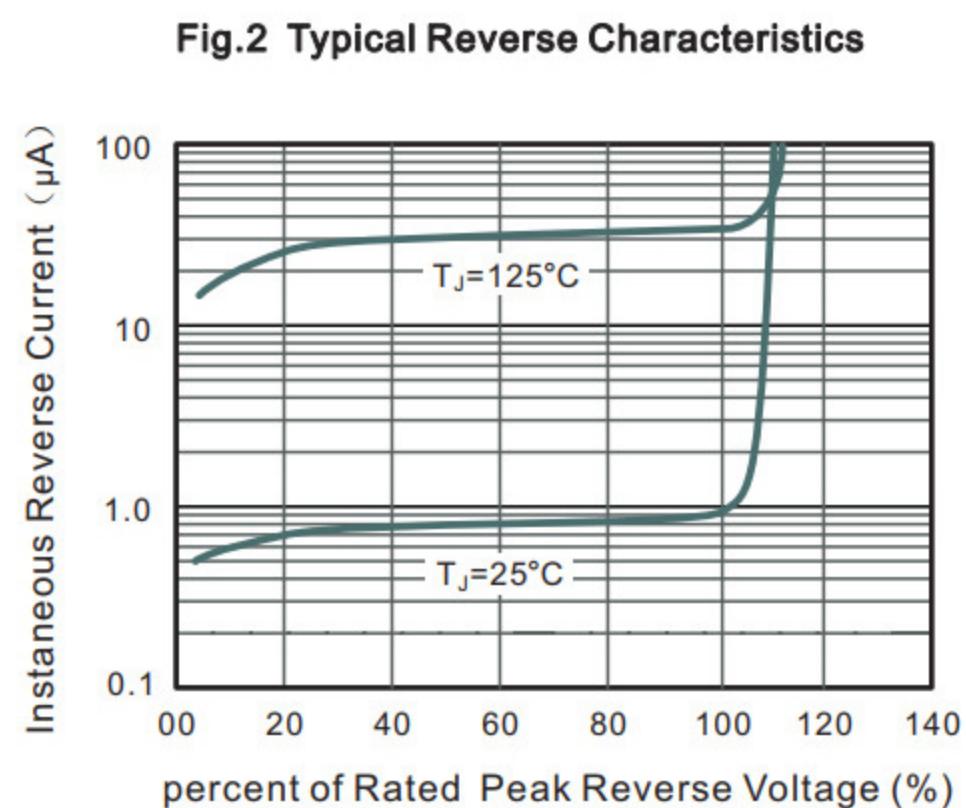
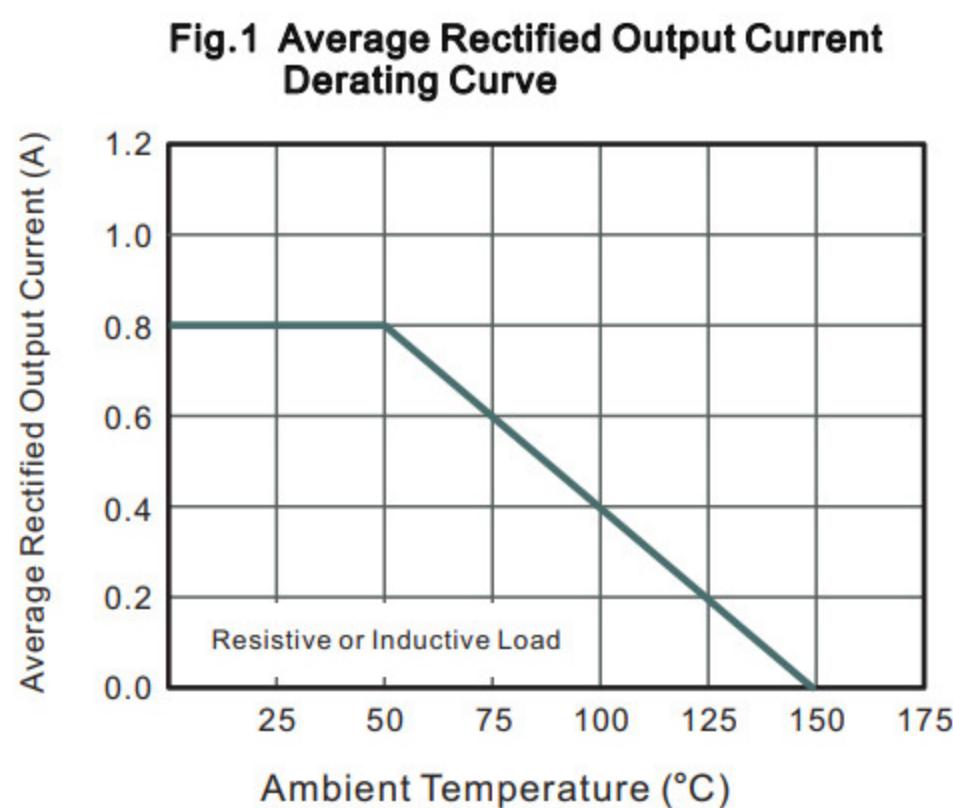
Ratings at 25 °C ambient temperature unless otherwise specified.

Single phase half-wave 60 Hz, resistive or inductive load, for capacitive load current derate by 20 %.

Parameter	Symbols	MB1S	MB2S	MB4S	MB6S	MB8S	MB10S	Units
Maximum Repetitive Peak Reverse Voltage	V_{RRM}	100	200	400	600	800	1000	V
Maximum RMS voltage	V_{RMS}	70	140	280	420	560	700	V
Maximum DC Blocking Voltage	V_{DC}	100	200	400	600	800	1000	V
Average Rectified Output Current at $T_a = 50^\circ\text{C}$	I_o	1.0						A
Peak Forward Surge Current 8.3 ms Single Half Sine Wave Superimposed on Rated Load (JEDEC Method)	I_{FSM}	30						A
Maximum Forward Voltage at 0.4 A at 0.8 A	V_F	1.0 1.1						V
Maximum DC Reverse Current at Rated DC Blocking Voltage $@T_a=25^\circ\text{C}$ $@T_a=125^\circ\text{C}$	I_R	5 40						μA
Typical Junction Capacitance (Note1)	C_j	13						pF
Typical Thermal Resistance (Note2)	$R_{\theta JA}$ $R_{\theta JL}$	95 30						$^\circ\text{C/W}$
Operating and Storage Temperature Range	T_j, T_{stg}	-55 ~ +150						$^\circ\text{C}$

Note: 1. Measured at 1MHz and applied reverse voltage of 4 V D.C.

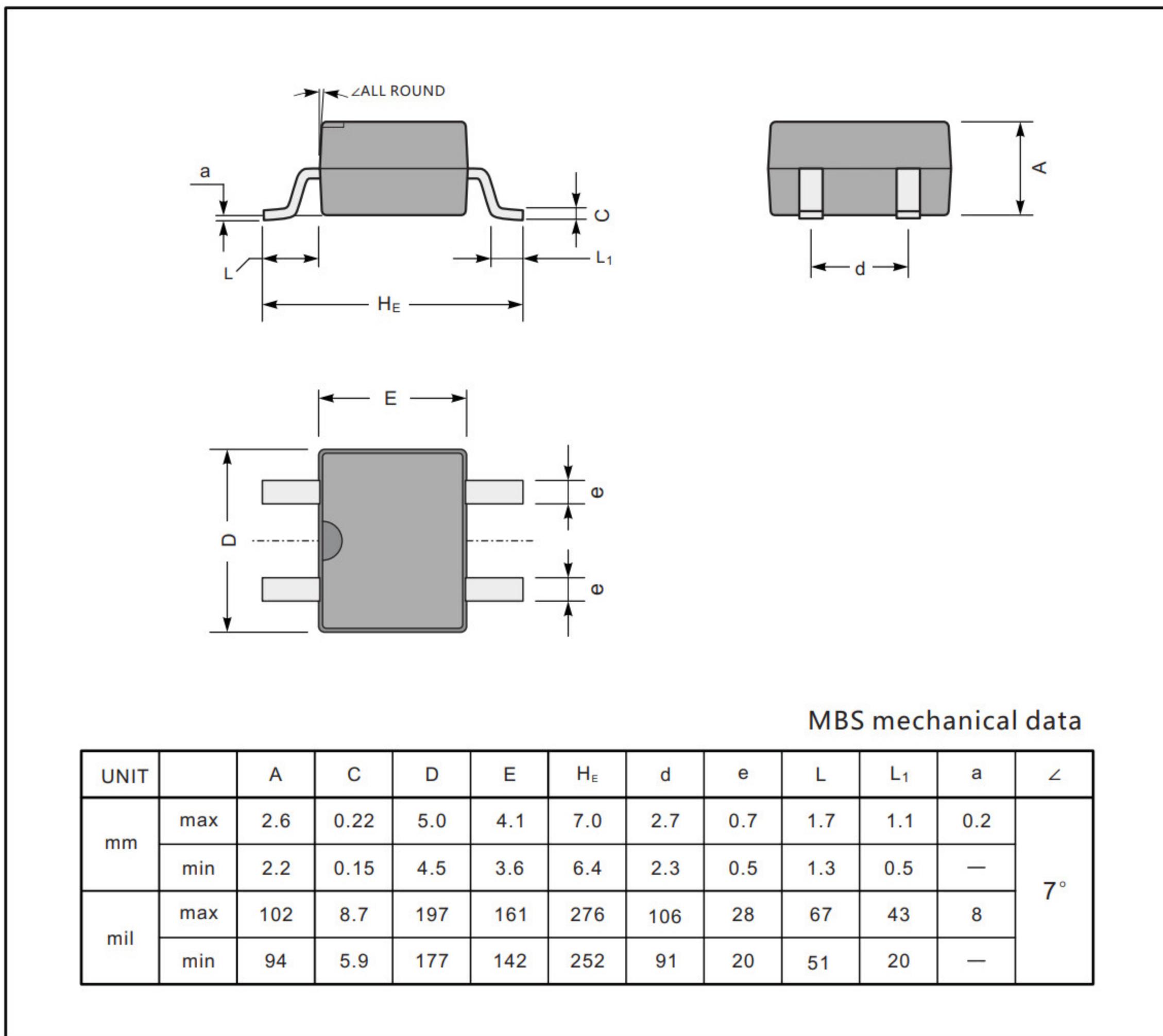
2. Mounted on glass epoxy PC board with $4 \times (5 \times 5\text{mm}^2)$ copper pad.



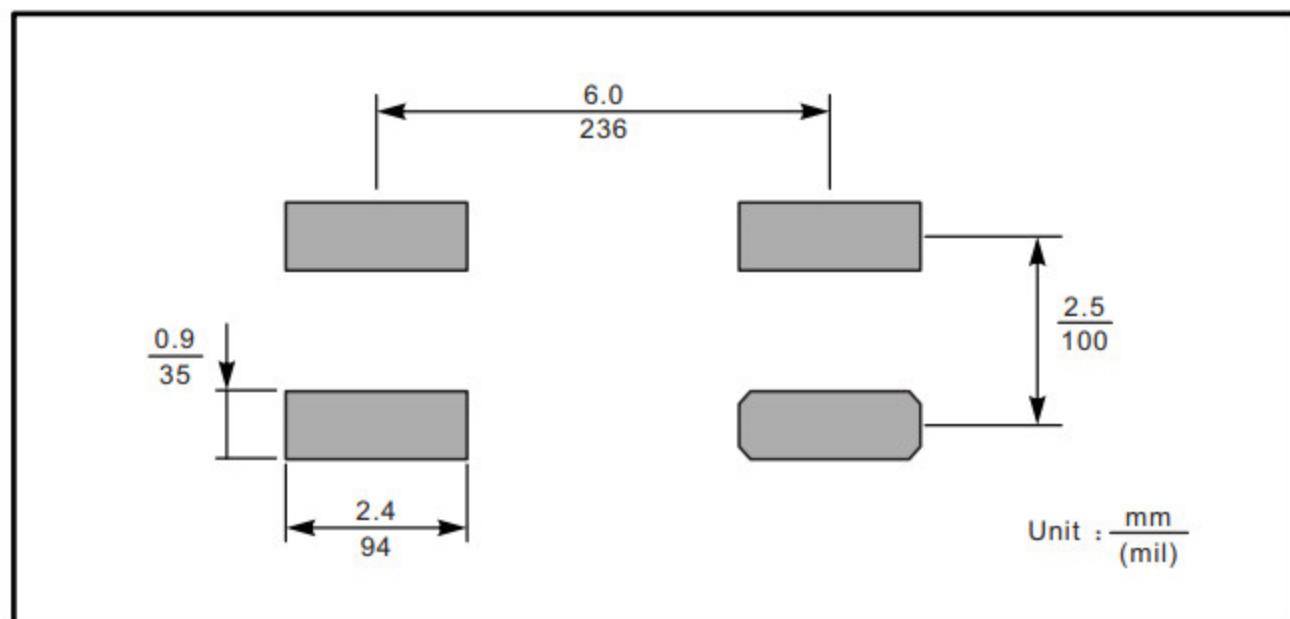
PACKAGE OUTLINE

Plastic surface mounted package; 4 leads

MBS



The recommended mounting pad size



Marking

Type number	Marking code
MB1S	MB1S
MB2S	MB2S
MB4S	MB4S
MB6S	MB6S
MB8S	MB8S
MB10S	MB10S